

IN THE ABSTRACT

Please add the following abstract from the International Application following page 45.

In a module including circuit elements, a plurality of wires, which are generally two-dimensionally formed, are multi-layered via electrically insulating material, which comprises a mixture including at least filler and electrically insulating resin. One or more circuit elements are electrically connected to the wires, and at least a part of those circuit elements is embedded in the electrically insulating material. The module further includes a heat sink member that has a higher thermal conductivity than the electrically insulating material, and that, when viewed from the direction of multi-layering the wires, overlaps with a circuit element, which is one of those circuit elements, exhibiting the highest temperature rise at least in the module.